

SOT640-1

plastic thin fine-pitch ball grid array package; 180 balls; body
10 x 10 x 0.8 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA180
Package type industry code	TFBGA180
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
Mounting method type	S (surface mount)
Issue date	3-3-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	1.11	1.11	mm
A ₂	package height	0.76	-	0.8	0.84	mm
n ₂	actual quantity of termination	-	-	180	-	



2. Package outline

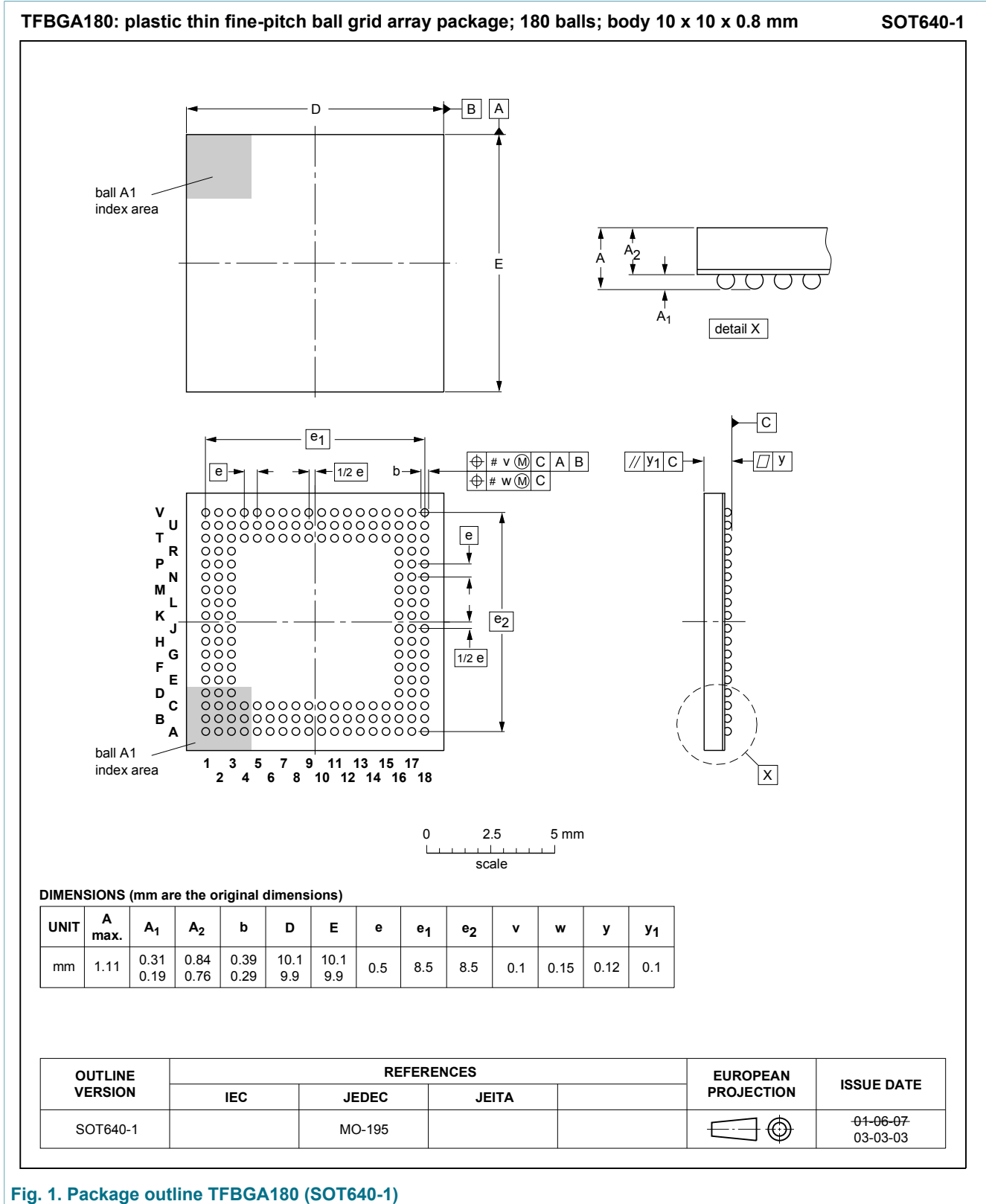


Fig. 1. Package outline TFBGA180 (SOT640-1)

3. Soldering

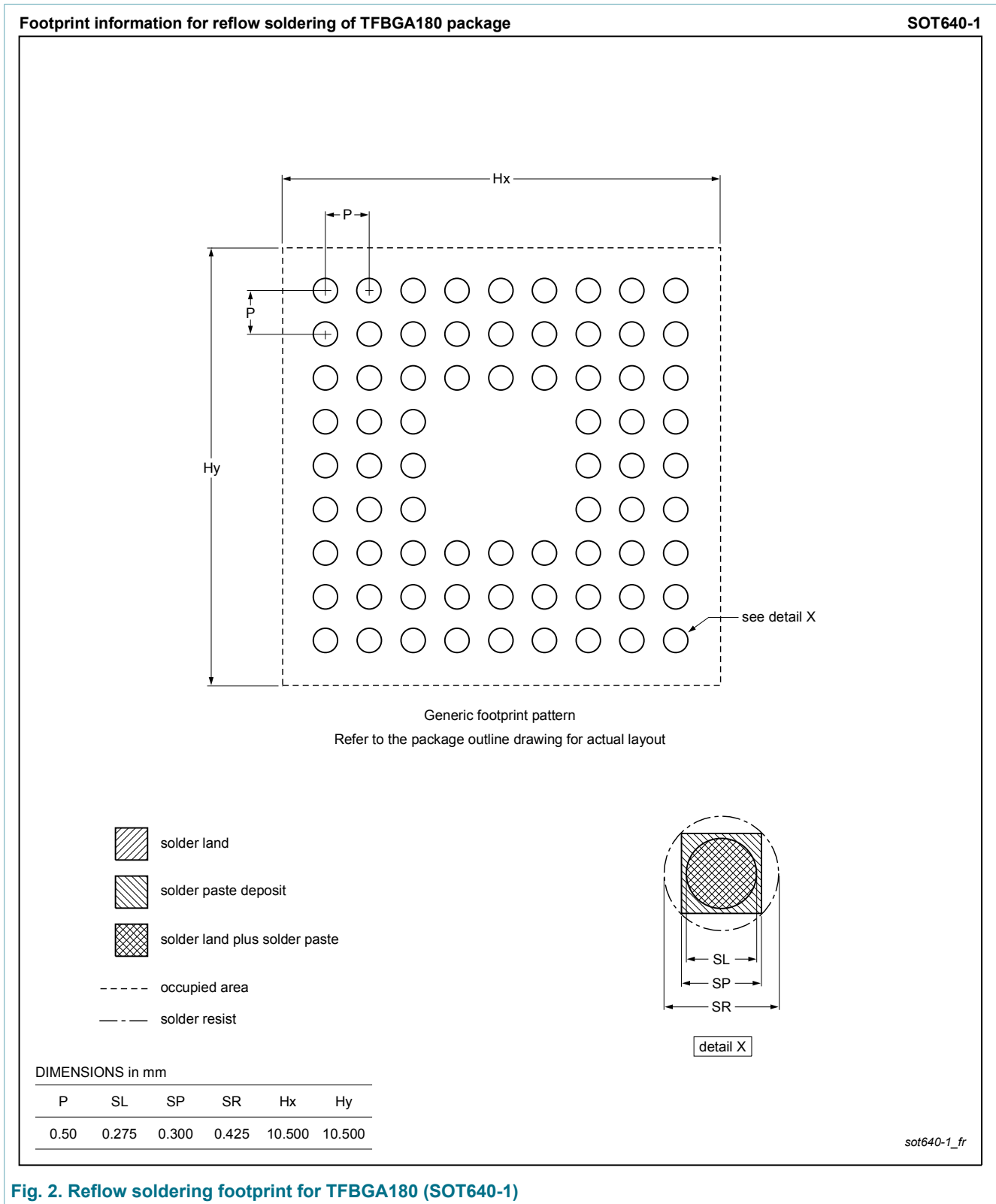


Fig. 2. Reflow soldering footprint for TFBGA180 (SOT640-1)

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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